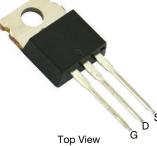


IXTP160N075T-VB Datasheet N-Channel 80 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω) MAX.	Q _g (TYP.)				
80	0.0028 at V_{GS} = 10 V	195	94			
	0.0030 at V_{GS} = 7.5 V	185	54			





FEATURES

- Trench power MOSFET
- Maximum 175 °C junction temperature
- Very low ${\rm Q}_{gd}$ reduces power loss from passing through ${\rm V}_{plateau}$
- 100 % R_g and UIS tested



COMPLIANT HALOGEN

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APPLICATIONS

- Power supply
 Secondary synchronous rectification
- DC/DC converter
- Power tools
- Motor drive switch
- DC/AC inverter
- Battery management



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ABSOLUTE MAXIMUM RATINGS ($T_c = 25 \text{ °C}$, unless otherwise noted)						
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-Source Voltage	V _{DS}	80	v			
Gate-Source Voltage	V _{GS}	± 20	v			
Continuous Drain Current (T. 150 °C)	T _C = 25 °C		195			
Continuous Drain Current (T _J = 150 °C)	T _C = 70 °C	ID	120 ^d	٨		
Pulsed Drain Current (t = 100 µs)	I _{DM}	600	A			
Avalanche Current		I _{AS}	70			
Single Avalanche Energy ^a	L = 0.1 mH	E _{AS}	245	mJ		
Maximum Power Dissipation ^a	T _C = 25 °C	Р	375 ^b	W		
	T _C = 125 °C	- P _D -	125 ^b			
Operating Junction and Storage Temperature F	lange	T _J , T _{stg}	-55 to +175	°C		

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	LIMIT	UNIT		
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	40	°C/W		
Junction-to-Case (Drain)	R _{thJC}	0.4	0/11		

Notes

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.
- c. When mounted on 1" square PCB (FR4 material).
- d. Package limited.

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-Source Breakdown Voltage	V _{DS}	V_{GS} = 0 V, I_D = 250 μ A	80	-	-	v	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	2	-	4		
Gate-Body Leakage	I _{GSS}	V_{DS} = 0 V, V_{GS} = ± 20 V	-	-	± 250	nA	
		$V_{DS}=80~V,~V_{GS}=0~V$	-	-	1	μΑ	
Zero Gate Voltage Drain Current	I _{DSS}	V_{DS} = 80 V, V_{GS} = 0 V, T_J = 125 °C	-	-	150		
		V_{DS} = 80 V, V_{GS} = 0 V, T_J = 175 $^\circ C$	-	-	5	mA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	120	-	-	А	
Drain-Source On-State Resistance a	Р	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 30 \text{ A}$	-	0.0028	-	Ω	
Drain-Source On-State Resistance ~	R _{DS(on)}	V_{GS} = 7.5 V, I_D = 20 A	-	0.0030	-		
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 30 \text{ A}$	-	82	-	S	
Dynamic ^b							
Input Capacitance	C _{iss}		-	7910	-	pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 V, V_{DS} = 40 V, f = 1 MHz$	-	3250	-		
Reverse Transfer Capacitance	C _{rss}		-	348	-		
Total Gate Charge ^c	Qg		-	94	141	nC	
Gate-Source Charge ^c	Q _{gs}	V_{DS} = 40 V, V_{GS} = 10 V, I_{D} = 20 A	-	31	-		
Gate-Drain Charge ^c	Q _{gd}		-	10	-		
Gate Resistance	Rg	f = 1 MHz	0.28	1.4	2.8	Ω	
Turn-On Delay Time ^c	t _{d(on)}		-	24	40		
Rise Time ^c	t _r	V_{DD} = 40 V, R_L = 4 Ω	-	24	40	- ns	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 10$ Å, $V_{GEN} = 10$ V, $R_g = 1$ Ω	-	34	60		
Fall Time ^c	t _f		-	14	28		
Drain-Source Body Diode Ratings ar	nd Characteris	stics ^b (T _C = 25 °C)					
Pulsed Current (t = 100 µs)	I _{SM}		-	-	250	А	
Forward Voltage ^a	V _{SD}	$I_F = 10 \text{ A}, V_{GS} = 0 \text{ V}$	-	0.8	1.5	V	
Reverse Recovery Time	t _{rr}		-	126	190	ns	
Peak Reverse Recovery Charge	I _{RM(REC)}	$I_F = 34$ A, di/dt = 100 A/µs	-	5	10	А	
Reverse Recovery Charge	Q _{rr}		-	0.315	0.475	μC	

Notes

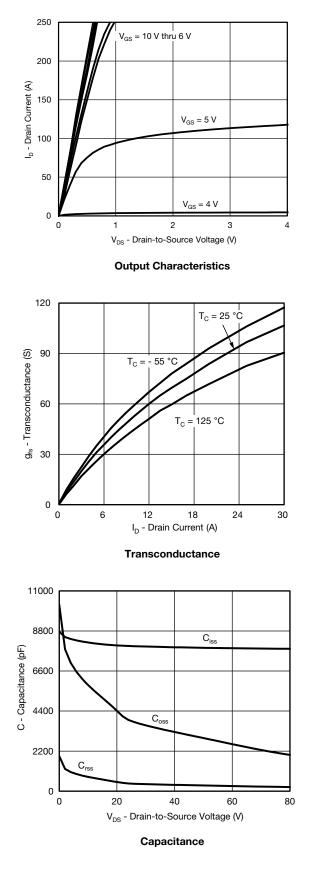
a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %.
b. Guaranteed by design, not subject to production testing.
c. Independent of operating temperature.

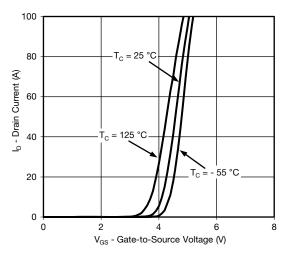
semi

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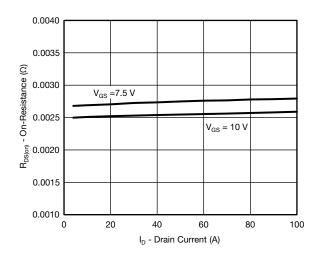


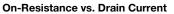
TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)

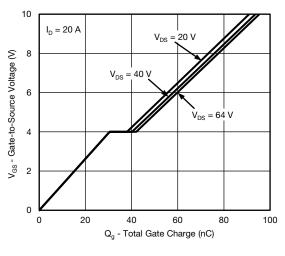




Transfer Characteristics



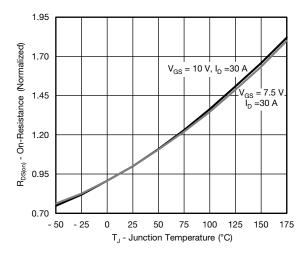




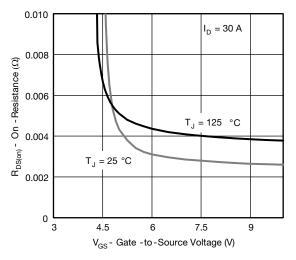




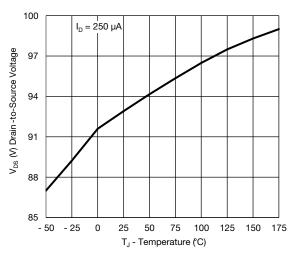
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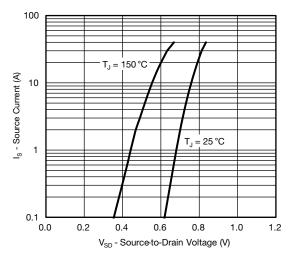
On-Resistance vs. Junction Temperature



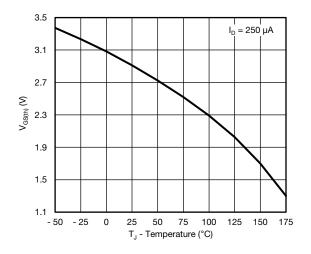
On-Resistance vs. Gate-to-Source Voltage



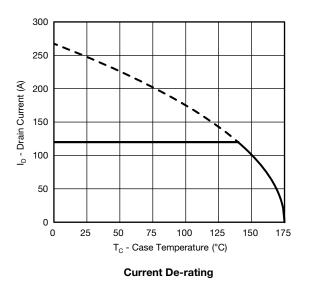
Drain Source Breakdown vs. Junction Temperature



Source Drain Diode Forward Voltage

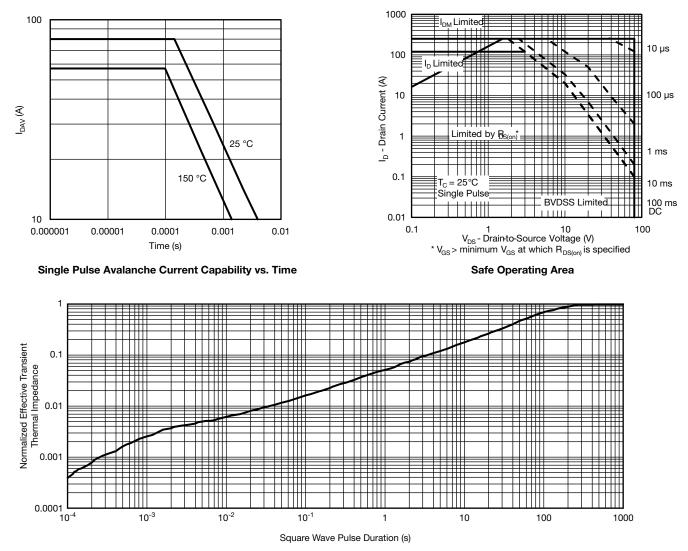








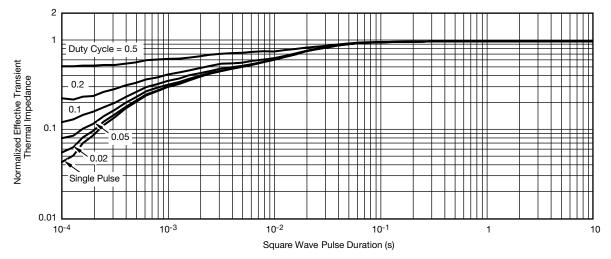
THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

Note

• The characteristics shown in the two graphs

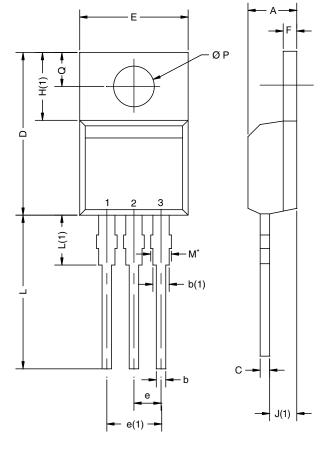
- Normalized Transient Thermal Impedance Junction to Ambient (25 °C)

- Normalized Transient Thermal Impedance Junction to Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



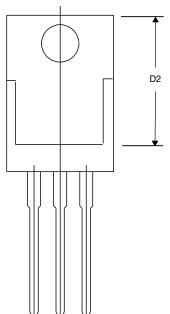
TO-220AB



	MILLIMETERS		INCHES	
DIM.	MIN.	MAX.	MIN.	MAX.
А	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
с	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
D2	12.19	12.70	0.480	0.500
E	10.04	10.51	0.395	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
ØР	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118
ECN: T14-0413-Rev. P, 16-Jun-14 DWG: 5471				

Note

* M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM





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